

## **II. AMENDMENTS TO THE SPECIFICATION**

On Page 1, lines 1 and 2, please change the title of the invention to:

~~METHOD OF PRODUCING SEMICONDUCTOR DEVICE AND GRINDING MACHINE  
FOR USE IN THE METHOD~~

METHOD OF PRODUCING A SEMICONDUCTOR DEVICE BY DIVIDING A  
SEMICONDUCTOR WAFER INTO SEPARATE PIECES OF SEMICONDUCTOR  
CHIPS (As Amended)

On page 1, after line 2 (title of the invention) and before line 3, please insert the following paragraph:

### RELATED APPLICATION

This application is a divisional application of Application No. 09/704,563, filed on  
November 3, 2000.